

CLAIMS

1. A thermoplastic resin composition containing 100 parts by weight of an amorphous thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the glass transition point of said thermoplastic resin.

2. A thermoplastic resin composition containing 100 parts by weight of an crystalline thermoplastic resin and 0.1 to 100 parts by weight of an inorganic compound dispersed in said thermoplastic resin, characterized in that not less than 75% of the shape of a molded article is maintained at temperatures above the melting point of said thermoplastic resin.

3. The thermoplastic resin composition according to claim 1 or 2, wherein the dispersion particle diameter of said inorganic compound is 2 μm or less.

4. The thermoplastic resin composition according to any one of claims 1 to 3, wherein said inorganic compound is an inorganic compound containing silicon and oxygen as a constituent element.

5. The thermoplastic resin composition according to any one of claims 1 to 4, wherein said inorganic compound is laminar silicate.

6. A material for substrates, characterized in that said material is composed by using the thermoplastic resin composition according to any one of claims 1 to 5.

7. A film for substrates, characterized in that said film is composed by using the thermoplastic resin composition according to any one of claims 1 to 5.